

Product	Laser diode
Package	RLD63NPC7

Materials	Flow chart			Name of process	Used equipment & machine	Controlled item
	Material acceptance	Preparatory process	Main Process			
LD chip	<pre> graph TD Start(()) --> M1[Material acceptance] M1 --> P1{1} P1 --> P2((2)) P2 --> P3{3} P3 --> P4((4)) P4 --> P5((5)) P5 --> P6{6} P6 --> P7((7)) P7 --> P8{8} P8 --> P9((9)) P9 --> P10{10} </pre>			Acceptance test	Visual	Appearance
Submount				Chips preparation	Braking machine Expander	Appearance Air pressure Temperature
				Acceptance test	Microscope	Appearance
				Die-&wire-bonding(1)	ALDW40	Temperature DB load Ultrasonic power WB load
				Measurement	ALDW40	Probe state I-L characteristics I-V characteristics
Stem				Inspection(1)	Tension gauge	Wire-pull resistivity Peel-off resistivity
Pin Photo Di				Die-&wire-bonding(0)	APDW	Temperature Ultrasonic power
Ag paste				Inspection(0)		PD,DB position Wire-pull resistivity
Bondhing agent				Die-&wire-bonding(2)	ASDW	Peel-off resistivity Temperature DB load Ultrasonic power
				Inspection(2)	Microscope Tension gauge FFP standard Correct monitorscope	Wire-pull resistivity DB load Facet inclination △XYZ

Materials	Flow chart			Name of process	Used equipment & machine	Controlled item
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Cap				Can sealing	AACL	Air pressure
				Inspection for sealing	Cutting nipper Micrometer Correct monitorscope	Weld strength Weld extrusion Degree of decentering
				Products burn-in test	AATB	Set temperature I-L characteristics (100% test)
				Final measurement Marking	ATMS	Temperature I-L characteristics I-V characteristics Positional accuracy FFP Wavelength Appearance (100% test)
				Appearance check	Microscope	Flaws of stem Paste deposition (100% test)
				Quantity treatment	Calculator	Quantity check
				Packing		Slip Indication check
				Shipment inspection		Outer label and contents check
				Packaging		Detailed statement for shipment Packing condition
				Shipment		

Notes

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